

# Schottky

High Performance Schottky Diode  
Low Loss and Soft Recovery  
Common Cathode

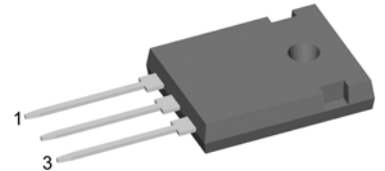
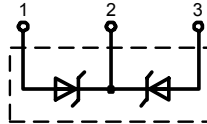
$$V_{RRM} = 60 \text{ V}$$

$$I_{FAV} = 2 \times 30 \text{ A}$$

$$V_F = 0.67 \text{ V}$$

Part number (Marking on product)

DSB 60 C 60HB



## Features / Advantages:

- Very low  $V_f$
- Extremely low switching losses
- Low  $I_{rm}$ -values
- Improved thermal behaviour
- High reliability circuit operation
- Low voltage peaks for reduced protection circuits
- Low noise switching
- Low losses

## Applications:

- Rectifiers in switch mode power supplies (SMPS)
- Free wheeling diode in low voltage converters

## Package:

TO-247AD

- Industry standard outline
- Epoxy meets UL 94V-0
- RoHS compliant

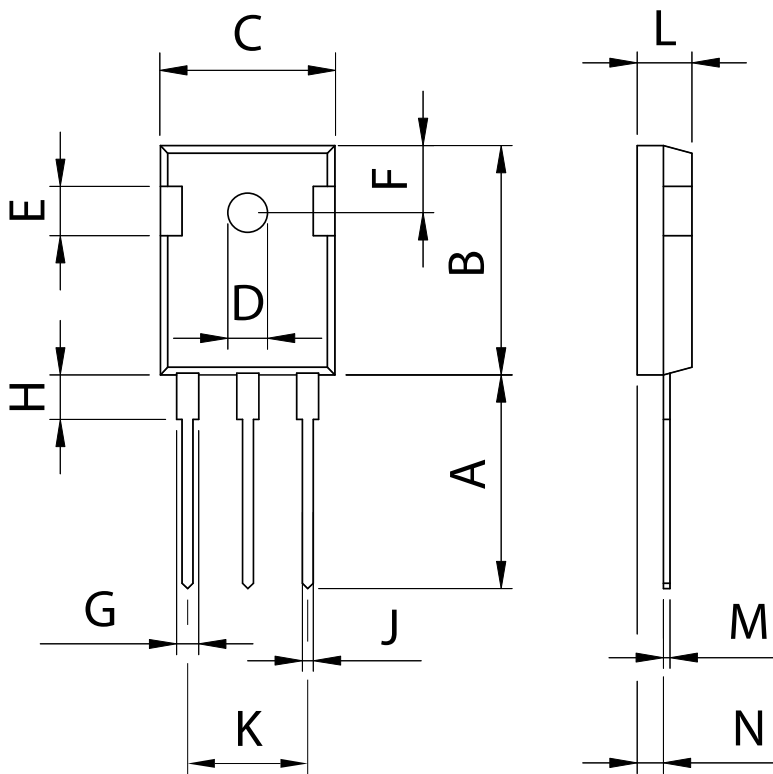
## Ratings

Symbol	Definition	Conditions	Ratings			Unit	
			min.	typ.	max.		
$V_{RRM}$	max. repetitive reverse voltage	$T_{VJ} = 25 \text{ }^\circ\text{C}$			60	V	
$I_R$	reverse current	$V_R = 60 \text{ V}$			20	mA	
		$V_R = 60 \text{ V}$			50	mA	
$V_F$	forward voltage	$I_F = 30 \text{ A}$			0.77	V	
		$I_F = 60 \text{ A}$			1.18	V	
		$I_F = 30 \text{ A}$	$T_{VJ} = 125 \text{ }^\circ\text{C}$			0.67	V
		$I_F = 60 \text{ A}$	$T_{VJ} = 125 \text{ }^\circ\text{C}$			0.92	V
$I_{FAV}$	average forward current	rectangular, $d = 0.5$			30	A	
$V_{F0}$	threshold voltage	} for power loss calculation only			0.46	V	
$r_F$	slope resistance				6.2	m $\Omega$	
$R_{thJC}$	thermal resistance junction to case				0.95	K/W	
$T_{VJ}$	virtual junction temperature		-55		150	$^\circ\text{C}$	
$P_{tot}$	total power dissipation	$T_C = 25 \text{ }^\circ\text{C}$			130	W	
$I_{FSM}$	max. forward surge current	$t_p = 10 \text{ ms (50 Hz), sine}$			320	A	
$C_j$	junction capacitance	$V_R = \text{ V; } f = 1 \text{ MHz}$				pF	
$E_{AS}$	non-repetitive avalanche energy	$I_{AS} = \text{ A; } L = 100 \text{ } \mu\text{H}$			tbd	mJ	
$I_{AR}$	repetitive avalanche current	$V_A = 1.5 \cdot V_R \text{ typ.; } f = 10 \text{ kHz}$			tbd	A	

Symbol	Definition	Conditions	Ratings			Unit
			min.	typ.	max.	
$I_{RMS}$	RMS current	per pin*			50	A
$R_{thCH}$	thermal resistance case to heatsink			0.25		K/W
$M_D$	mounting torque		0.8		1.2	Nm
$F_c$	mounting force with clip		20		120	N
$T_{stg}$	storage temperature		-55		150	°C
<b>Weight</b>				6		g

\*  $I_{rms}$  is typically limited by: 1. pin-to-chip resistance; or by 2. current capability of the chip.

In case of 1, a common cathode/anode configuration and a non-isolated backside, the whole current capability can be used by connecting the backside.

**Outlines TO-247AD**


Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	19.81	20.32	0.780	0.800
B	20.80	21.46	0.819	0.845
C	15.75	16.26	0.610	0.640
D	3.55	3.65	0.140	0.144
E	4.32	5.49	0.170	0.216
F	5.4	6.2	0.212	0.244
G	1.65	2.13	0.065	0.084
H	-	4.5	-	0.177
J	1.0	1.4	0.040	0.055
K	10.8	11.0	0.426	0.433
L	4.7	5.3	0.185	0.209
M	0.4	0.8	0.016	0.031
N	1.5	2.49	0.087	0.102